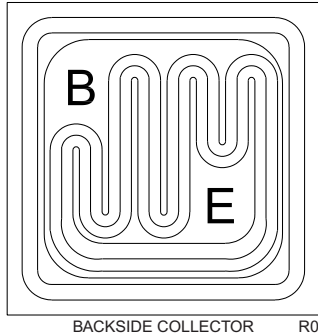


CP235-2N3055

NPN - High Current Transistor Die

15 Amp, 60 Volt

The CP235-2N3055 die is a silicon NPN transistor designed for high current applications.



MECHANICAL SPECIFICATIONS:

Die Size	106 x 106 MILS
Die Thickness	12 MILS
Base Bonding Pad Size	25 x 33 MILS
Emitter Bonding Pad Size	30 x 36 MILS
Top Side Metalization	Al - 50,000Å
Back Side Metalization	Ag - 10,000Å
Scribe Alley Width	4.0 mils
Wafer Diameter	4 INCHES
Gross Die Per Wafer	920

MAXIMUM RATINGS: (T_C=25°C)

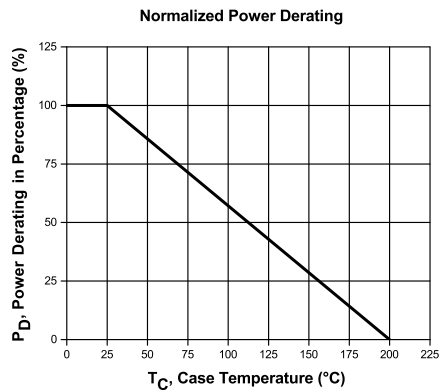
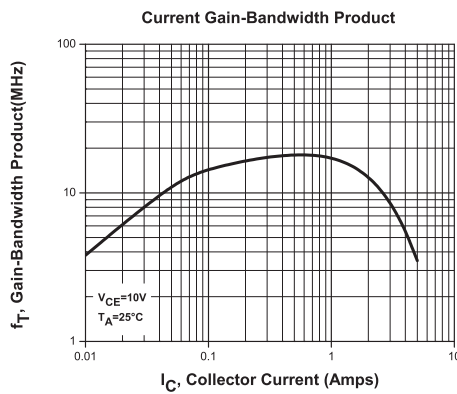
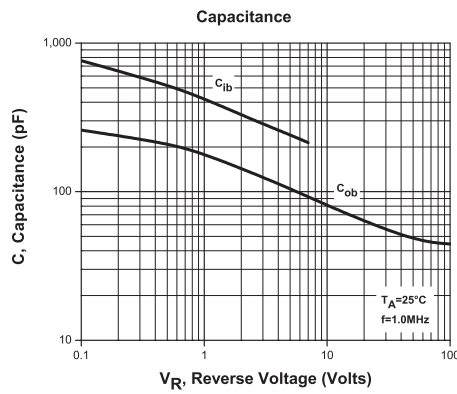
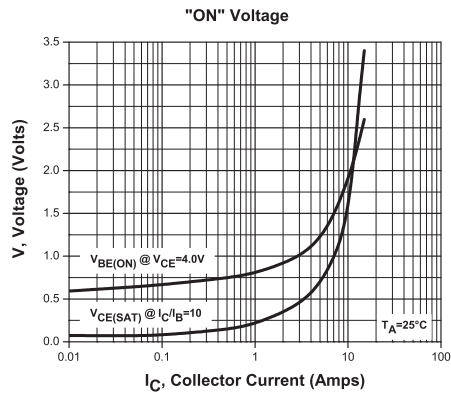
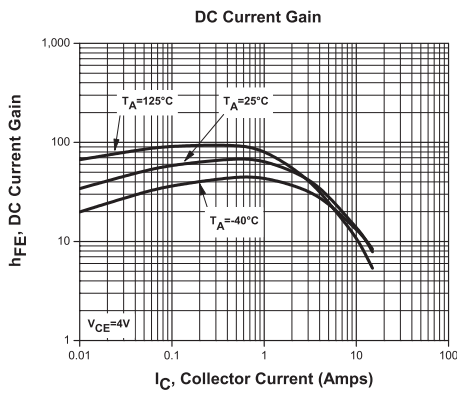
	SYMBOL		UNITS
Collector-Base Voltage	V _{CBO}	100	V
Collector-Emitter Voltage	V _{CER}	70	V
Collector-Emitter Voltage	V _{CEO}	60	V
Emitter-Base Voltage	V _{EBO}	7.0	V
Continuous Collector Current	I _C	15	A
Continuous Base Current	I _B	7.0	A
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +200	°C

ELECTRICAL CHARACTERISTICS: (T_C=25°C unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I _{CEV}	V _{CE} =100V, V _{EB} =1.5V		1.0	mA
I _{CEO}	V _{CE} =30V		0.7	mA
I _{EBO}	V _{EB} =7.0V		5.0	mA
BV _{CEO}	I _C =200mA	60		V
BV _{CER}	I _C =200mA, R _{BE} =100Ω	70		V
V _{CE(SAT)}	I _C =4.0A, I _B =400mA		1.1	V
V _{CE(SAT)}	I _C =10A, I _B =3.3A		3.0	V
V _{BE(ON)}	V _{CE} =4.0V, I _C =4.0A		1.5	V
h _{FE}	V _{CE} =4.0V, I _C =4.0A	20	70	
h _{FE}	V _{CE} =4.0V, I _C =10A	5.0		
h _{fe}	V _{CE} =4.0V, I _C =1.0A, f=1.0kHz	15	120	
f _T	V _{CE} =10V, I _C =0.5A, f=1.0MHz	2.5		MHz
f _{hfe}	V _{CE} =4.0V, I _C =1.0A, f=1.0kHz	10		kHz
I _{s/b}	V _{CE} =40V, t=1.0s	2.87		A

CP235-2N3055

Typical Electrical Characteristics



BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

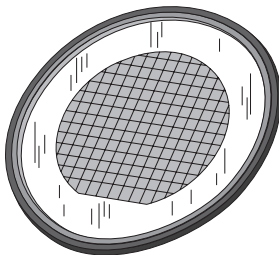
CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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